WHAT IS CLAIMED IS:

1. A method for manufacturing a printed circuit board comprising:

washing a land that corresponds to an exposed portion of a copper circuit of a printed circuit board with acidic electrolytic water having a pH of not more than 5 to remove an oxide;

treating the land with basic electrolytic water having a pH of not less than 9 to prevent oxidation; and

soldering electronic components to the land.

2. The method according to claim 1, wherein the acidic electrolytic water has a pH of not more than 4.

3. The method according to claim 2, wherein the acidic electrolytic water has a pH of not more than 3.

4. The method according to claim 1, wherein the basic electrolytic water has a pH of not less than 10.

5. The method according to claim 4, wherein the basic electrolytic water has a pH of not less than 11.

6. The method according to claim 1, wherein application of the acidic electrolytic water or the basic electrolytic water to the land is performed by spraying.

7. The method according to claim 1, wherein application of the acidic electrolytic water or the basic electrolytic water to the land is performed by immersion.

8. The method according to claim 1, wherein washing with the acidic electrolytic water and oxidation prevention with the basic electrolytic water are performed successively as a pretreatment before soldering electronic components to the printed circuit board.

9. The method according to claim 1 wherein, the acidic electrolytic water that has been used for washing and the basic electrolytic water that

has been used for oxidation prevention are mixed and drained.

10. The method according to claim 9, wherein the acidic electrolytic water and the basic electrolytic water are mixed to create neutral water, and the neutral water is drained.

11. The method according to claim 1, wherein the land of the printed circuit board is a copper-plated land that surrounds a through hole provided in a substrate.

12. The method according to claim 1, wherein the land of the printed circuit board is a land on which an electronic component or semiconductor is mounted.